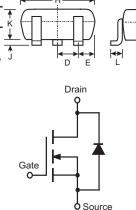




## N-CHANNEL ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

### **Features**

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- Lead Free/RoHS Compliant (Note 2)
- "Green" Device (Note 3 and 4)
- Mechanical Data
- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Marking (See Page 2): K72
- Ordering & Date Code Information: See Page 2
- Weight: 0.006 grams (approximate)



вС

SOT-323									
Dim	Min	Мах							
Α	0.25	0.40							
В	1.15	1.35							
С	2.00	2.20							
D	0.65 N	ominal							
E	0.30	0.40							
G	1.20	1.40							
Н	1.80	2.20							
J	0.0	0.10							
К	0.90	1.00							
L	0.25	0.40							
М	0.10	0.18							
α	0°	8°							
All Dimensions in mm									

## Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified

Charact	eristic	Symbol	2N7002W	Units		
Drain-Source Voltage		V <sub>DSS</sub>	60	V		
Drain-Gate Voltage $R_{GS} \le 1.0I$	MΩ	V <sub>DGR</sub>	60	V		
Gate-Source Voltage Continuous Pulsed		V <sub>GSS</sub>	±20 ±40	V		
Drain Current (Note 1) Continuous Continuous @ 100°C Pulsed		ID	115 73 800	mA		
Total Power Dissipation (Note Derating above $T_A = 25^{\circ}C$	1)	Pd	200 1.60	mW mW/°C		
Thermal Resistance, Junction	to Ambient	R <sub>θJA</sub>	625	K/W		
Operating and Storage Tempe	erature Range	Tj, T <sub>STG</sub>	-55 to +150	°C		

Note: 1. Device mounted on FR-5 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

2. No purposefully added lead.

3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.

4. Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product

manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.



lectrical Chacteristics	@ T <sub>A</sub> = 25°C un	less otherv	vise spec	cified				
Characteristic	Symbol Min		Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 5)					1	•	I	
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	60	70	_	V	$V_{GS} = 0V, I_D = 10\mu A$	
Zero Gate Voltage Drain Current @ $T_C = 25^{\circ}C$ @ $T_C = 125^{\circ}C$		I <sub>DSS</sub>	_	_	1.0 500	μA	$V_{DS} = 60V, V_{GS} = 0V$	
Gate-Body Leakage		IGSS		_	±10	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 5)							•	
Gate Threshold Voltage		V <sub>GS(th)</sub>	1.0		2.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance	@ T <sub>j</sub> = 25°C @ T <sub>j</sub> = 125°C	R <sub>DS (ON)</sub>		1.8 2.6	7.5 13.5	0	$V_{GS} = 5.0V, I_D = 0.05A$	
	@ T <sub>j</sub> = 125°C					52	$V_{GS} = 10V, I_D = 0.5A$	
On-State Drain Current		I <sub>D(ON)</sub>	0.5	1.0		A	$V_{GS} = 10V, V_{DS} = 7.5V$	
Forward Transconductance		<b>g</b> fs	80		_	mS	$V_{DS} = 10V, I_D = 0.2A$	
DYNAMIC CHARACTERISTICS							•	
Input Capacitance		Ciss		22	50	pF		
Output Capacitance				11	25	pF	$V_{DS} = 25V, V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance				2.0	5.0	pF		
SWITCHING CHARACTERISTICS					1			
Turn-On Delay Time		t <sub>D(ON)</sub>		7.0	20	ns	$V_{DD} = 30V, I_D = 0.2A,$	
Turn-Off Delay Time			_	11	20	ns	$R_L = 150\Omega$ , $V_{GEN} = 10V$ , $R_{GEN} = 25\Omega$	

# Ordering Information (Note 4 and 6)

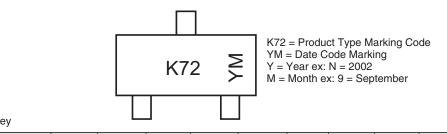
Device	Packaging	Shipping		
2N7002W-7-F	SOT-323	3000/Tape & Reel		

Notes: 4. Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

5. Short duration test pulse used to minimize self-heating effect.

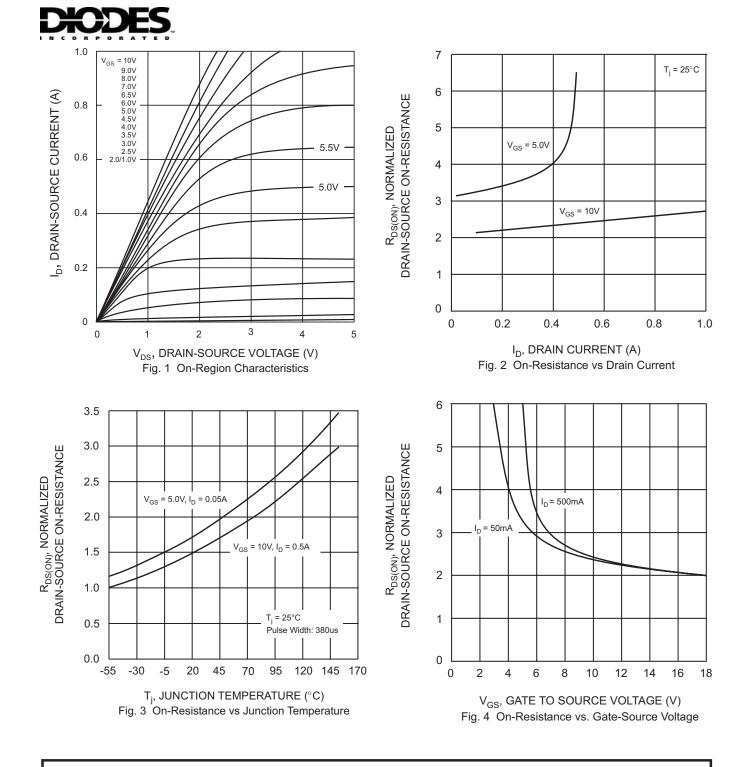
6. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

# **Marking Information**



Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009
Code	J	К	L	М	Ν	Р	R	S	Т	U	V	W
Month Jan Feb March Apr May Jun Jul Aug Sep Oct Nov Dec												
Code	1	2	3	4	5	6	7	8	9	0	N	D



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